

Please amend the following claims as presented, below, in clean-unmarked format:

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2. (Amended) The package of claim 1, wherein the package is a ball grid array package.

3. (Amended) The package of claim 1, wherein the package is a pin grid array package.

4. (Amended) The package of claim 1, wherein the die is attached to the lid, and the lid serves to conduct heat away from the die.

5. (Amended) The package of claim 1, wherein a vent-hole is formed through the lid.

6. (Amended) The package of claim 1, wherein the pattern in which the sealant is disposed between the lid and the substrate is a substantially rectangular pattern with at least one break.

7. (Amended) The package of claim 6, wherein the rectangular pattern has four breaks, one in each side of the substantially rectangular pattern.

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cont.

8. (Amended) The package of claim 7, wherein the four breaks comprise a minimum 10% of the total length of what would otherwise be an unbroken substantially rectangular pattern.
9. (Amended) The package of claim 6, wherein the rectangular pattern has four breaks, one in each corner of the substantially rectangular pattern.
10. (Amended) The package of claim 9, wherein the four breaks comprise a minimum 10% of the total length of what would otherwise be an unbroken substantially rectangular pattern.
11. (Amended) The package of claim 1, wherein the substrate is susceptible to absorbing moisture, and the pressure existing between the substrate and the lid is as a result of moisture being released within the package by the substrate and being converted to steam.
12. (Amended) The package of claim 11, wherein the substrate is comprised of organic material.
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24. (Amended) The electronic device of claim 23, wherein the die is attached to the lid, and the lid serves to conduct heat away from the die.
25. (Amended) The electronic device of claim 23, wherein the pattern in which the sealant is disposed between the lid and the substrate is a substantially rectangular pattern with at least one break.
26. (Amended) The electronic device of claim 25, wherein the rectangular pattern has four breaks, one in each side of the substantially rectangular pattern.
27. (Amended) The electronic device of claim 23, wherein the die is attached to the substrate using a controlled collapsed chip connection.
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REMARKS

Claims 1-14 and 23-27 are pending in this application.

Claims 15-22 have been cancelled.

Claims 2-12 and 24-27 have been amended.

A restriction to one invention under 35 U.S.C. §121 was communicated to Applicant with claims 1-14 and 23-27 being deemed to be drawn to invention I and claims 15-22 being deemed to be drawn to invention II, and Applicant makes a provisional election without traverse to prosecute claims 1-14 and 23-27, of invention I.